As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and attizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD FOR ENCAPSULATING INTERMEDIATE CONDUCTIVE ELEMENTS CONNECTING A SEMICONDUCTOR DIE TO A SUBSTRATE AND SEMICONDUCTOR DEVICES SO PACKAGED, the specification of which (check one):

•	cono).					
is attached hereto.						
□ was filed on		tes application serial no	and was amen	ded on		
□ was filed on	as PCT intern	ational application no	and was amende	ed under PCT Article 19	on	
I hereby state that I have referred to above.	reviewed and under	stand the contents of the above	identified specificati	on, including the claims	, as amended by a	ny amendment
		. Patent and Trademark Office fined in Title 37, Code of Federal			the patentability	of the subject matter
I hereby claim foreign pri	ority benefits unde	Title 35, United States Code,	8 119(a)-(d) or 8 365	(b) of any foreign applic	eation(s) for patent	t or inventor's
certificate or § 365(a) of any attached continuation page a	PCT international and have also dentif	application(s) designating at least one country other than the	ast one country other continuation page an	than the United States or y foreign application for	f America listed b patent or invento	elow and on any r's certificate or any
Prior foreign/PCT application	n(s):					
200103014-7		Singapore	7	May 21, 2001	Priority Claimed X	
(number)		(country)	(day/	month/year filed)	$\frac{X}{Yes}$	No
(number)		(country)	` •	month/year filed)	Yes	No
application is not disclosed in duty to disclose to the U.S. P	n any such prior ap atent and Trademan	ited States Code, § 120 of any below and on any attached con- plication in the manner provide k Office all information known ween the filing date of such prior	ed by the first paragrant to me to be material	ph of Title 35, United Stope to patentability as defin	tates Code, § 112, ned in Title 37, Co	I acknowledge the de of Federal
application serial no.)		(filing date)		(status - pending, patented or abandoned)		
= (application serial no.)		(filing date)		(status - pending,)	patented or abando	oned)
hereby claim the benefi	t under Title 35, Ur	ited States Code, § 119(e) of a	ny United States prov			
(provisional applicatio	n no.)	(filing date)				
	wing Registe ed Pro	actitioners to prosecute this app	plication and to transa	ct all business in the Pa	tent and Trademar	rk Office connected
David V. Trask, Reg. No Joseph A. Walkowski, Re Allen C. Turner, Reg. No Brick G. Power, Reg. No Krista Weber Powell, Reg. Shawn G. Hansen, Reg. Katherine A. Hamer, Reg	eg. No. 28,765 . 33,041 . 38,581 g. No. 47,867 No. 42,627	William S. Britt, Reg. No. 2 James R. Duzan, Reg. No. Edgar R. Cataxinos, Reg. No. Paul C. Oestreich, Reg. No. Jarett K. Abramson, Reg. 1 Bretton L. Crockett, Reg. 1 Michael L. Lynch, Reg. No.	28,393 No. 39,931 . 44,983 No. 47,376 No. 44,632	Laurence B. Bond, R H. Dickson Burton, I Kent S. Burningham, Devin R. Jensen, Reg David L. Stott, Reg. Bradley B. Jensen, R Charles B. Brantley I	Reg. No. P-48,39 , Reg. No. 30,453 z. No. 44,805 No. 43,937 eg. No. 46,801	
Address all correspondence t	TRAS P.O.	oh A. Walkowski, telephone no SKBRITT, PC BOX 2550 Lake City, Utah 84110	o. (801) 532-1922.			
further that these statements	were made with the	ein of my own knowledge are t knowledge that willful false st de and that such willful false s	tatements and the like	so made are punishable	by fine or imprise	onment, or both, unde
Full name of first joint inventor's signature		i	Date	·		
Residence: Singapore Citizenship: Republic of Sir	ngapore	oh #04-100, Singapore 310239				
Full name of second joint inventor's signature	ventor: Lee Fian C	hai	Date	;		
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DECLARATION FOR PATENT APPLICAT

(continuation page)

Invention title: METHOD FOR ENCAPS JLATING INTERMEDIATE CONDUCTIVE ELEMENTS CONNECTING A SEMICONDUCTOR DIE TO A SUBSTRATE AND SEMICONDUCTOR DEVICES SO PACKAGED

Inventor name(s) appearing on first declaration page: Chon Chin Hui

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1		
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